

### Features

- Low profile package
- Ideal for automated placement
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:  
260°C/10 seconds at terminals
- Component in accordance to  
RoHS 2002/95/1 and WEEE 2002/96/EC



SMAF

### Mechanical Data

- **Case:** SMAF molded plastic
- **Terminals:** Solder plated, solderable per  
JESD22-B102D
- **Polarity:** Laser band denotes cathode end

### Major Ratings and Characteristics

|                    |                                   |
|--------------------|-----------------------------------|
| $I_{F(AV)}$        | 3.0A                              |
| $V_{RRM}$          | 20 V to 200 V                     |
| $I_{FSM}$          | 100A                              |
| $V_F$              | 0.50V, 0.55V, 0.70V, 0.85V, 0.95V |
| $T_j \text{ max.}$ | 125 °C                            |

### Maximum Ratings & Thermal Characteristics

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

| Items                                                                              | Symbol          | SS32        | SS33 | SS34 | SS35 | SS36 | SS38 | SS310 | SS315 | SS320 | UNIT             |
|------------------------------------------------------------------------------------|-----------------|-------------|------|------|------|------|------|-------|-------|-------|------------------|
| Maximum repetitive peak reverse voltage                                            | $V_{RRM}$       | 20          | 30   | 40   | 50   | 60   | 80   | 100   | 150   | 200   | V                |
| Maximum RMS voltage                                                                | $V_{RMS}$       | 14          | 21   | 28   | 35   | 42   | 56   | 70    | 105   | 140   | V                |
| Maximum DC blocking voltage                                                        | $V_{DC}$        | 20          | 30   | 40   | 50   | 60   | 80   | 100   | 150   | 200   | V                |
| Maximum average forward rectified current                                          | $I_{F(AV)}$     | 3           |      |      |      |      |      |       |       |       | A                |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | $I_{FSM}$       | 100         |      |      |      |      |      |       |       |       | A                |
| Voltage rate of change (rated $V_R$ )                                              | dv/dt           | 10000       |      |      |      |      |      |       |       |       | V/ $\mu\text{s}$ |
| Thermal resistance from junction to lead <sup>(1)</sup>                            | $R_{\theta JL}$ | 25          |      |      |      |      |      |       |       |       | °C/W             |
| Operating junction and storage temperature range                                   | $T_J, T_{STG}$  | -65 to +125 |      |      |      |      |      |       |       |       | °C               |

Note 1: Mounted on P.C.B. with 0.28 x 0.28" (7.0 x 7.0mm) copper pad areas.

### Electrical Characteristics

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

| Items                         | Test conditions  |                    | Symbol | SS32 | SS33~34 | SS35~36 | SS38~310 | SS315~320 | UNIT |
|-------------------------------|------------------|--------------------|--------|------|---------|---------|----------|-----------|------|
| Instantaneous forward voltage | $I_F=3.0A^{(2)}$ |                    | $V_F$  | 0.50 | 0.55    | 0.70    | 0.85     | 0.95      | V    |
| Reverse current               | $V_R=V_{DC}$     | $T_j=25^{\circ}C$  | $I_R$  | 0.5  |         |         |          |           | mA   |
|                               |                  | $T_j=100^{\circ}C$ |        | 5.0  |         |         |          |           |      |

Note 2: Pulse test:300 $\mu\text{s}$  pulse width,1% duty cycle.

### Characteristic Curves ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

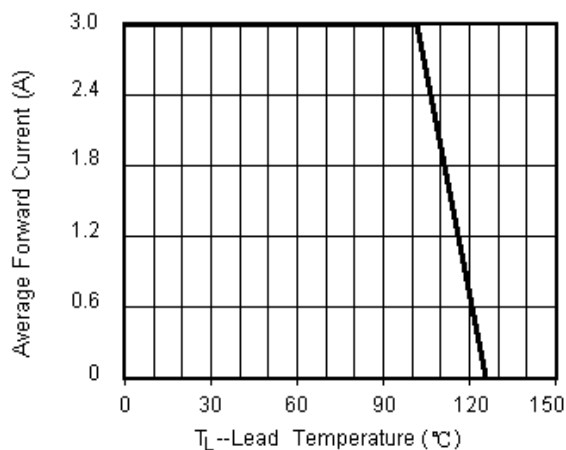


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

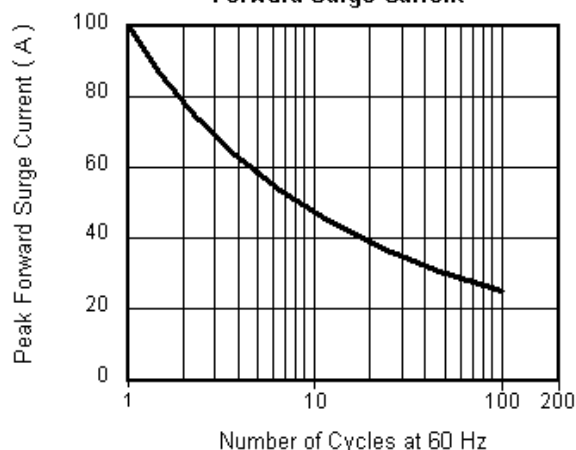


Fig.3 Typical Instantaneous Forward Characteristics

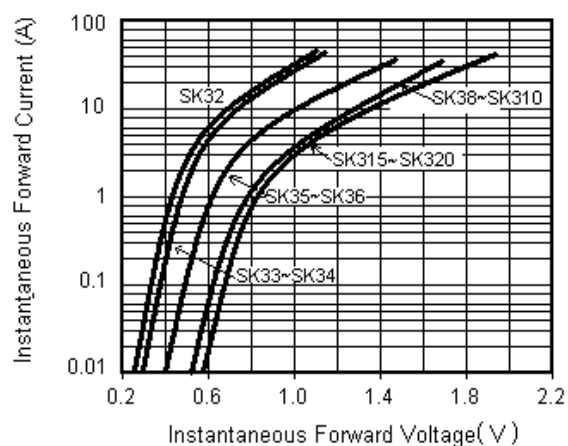
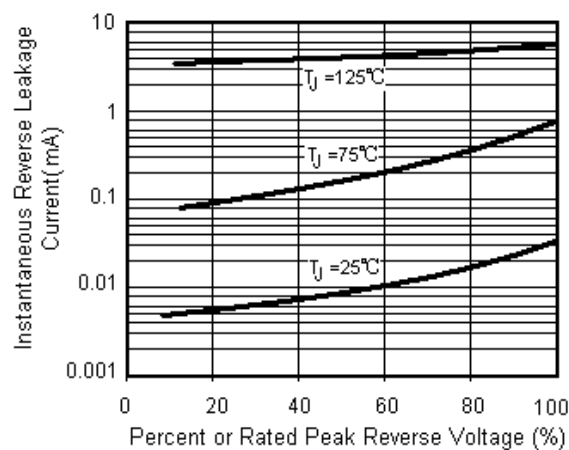
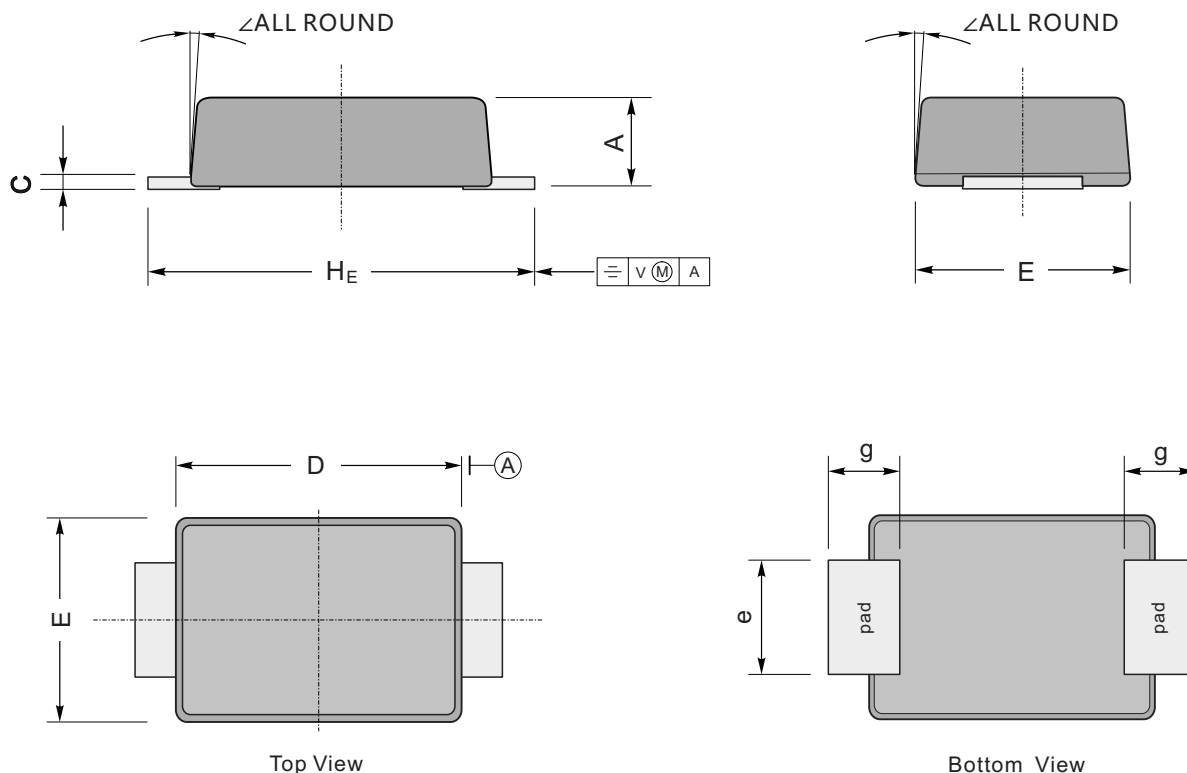


Fig.4 Typical Reverse Leakage Characteristics



### Package Outline



| UNIT |     | A   | C    | D   | E   | e   | g   | H <sub>E</sub> | ∠  |
|------|-----|-----|------|-----|-----|-----|-----|----------------|----|
| mm   | max | 1.1 | 0.20 | 3.7 | 2.7 | 1.6 | 1.2 | 4.9            | 7° |
|      | min | 0.9 | 0.12 | 3.3 | 2.4 | 1.3 | 0.8 | 4.4            |    |
| mil  | max | 43  | 7.9  | 146 | 106 | 63  | 47  | 193            |    |
|      | min | 35  | 4.7  | 130 | 94  | 51  | 31  | 173            |    |

### Notice

- Product is intended for use in general electronics applications.
- Product should be worked less than the ratings; if exceeded, may cause permanent damage or introduce latent failure mechanisms.
- The absolute maximum ratings are rated values and must not be exceeded during operation. The following are the general derating methods you design a circuit with a device.  
 $I_{F(AV)}$ : We recommend that the worst case current be no greater than 80% .  
 $T_J$ : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a  $T_J$  of below 100°C.

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